GP 2823

**DOCKET NO.: MERCHANT 33-3-3** 



**PATENT** 

TC 2800 MAIL ROOM

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sailesh Merchant, et al.

Serial No.:

09/092,158

Filed:

June 6, 1998

For:

METHOD FOR THE FABRICATION OF CONTACTS IN AN

INTEGRATED CIRCUIT DEVICE

Group No.:

2823

Examiner:

Eaton, K.

Commissioner of Patents and Trademarks Washington, D.C. 20231

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(Signature of the person signing the certificate)

Sir:

## AMENDMENT UNDER 37 C.F.R. § 1.111

In response to the Examiner's Action mailed December 28, 1999, please amend the above-identified application as follows:

## **IN THE SPECIFICATION:**

On page 8, line 15 after "process.", insert as a new paragraph—In another embodiment, the method further includes forming an active device on a semiconductor substrate, forming a contact opening in a dielectric deposited on the active device wherein the contact opening is in electrical contact with the active device, depositing a barrier layer in the contact opening and on at least a portion of the semiconductor substrate, depositing a contact metal on the barrier layer

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